

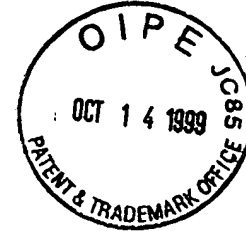
CAFFEY, HALTER & GRISWOLD
ATTORNEYS AT LAW

1400 McDonald Investment Center
800 Superior Avenue Cleveland, Ohio 44114-2688
216/622-8200 Fax 216/241-0816

Direct Dial No. 216/622-8636
email: jrich@calfee.com

October 12, 1999

Assistant Commissioner for Patents
U.S. Patent and Trademark Office
Washington, D.C. 20231



Re: Application of Gedney et al.
For: **IC CHIP ATTACHMENT**
CH&G No.: EN9-91-022R (21325/00276)

TECHNOLOGY CENTER 2800

OCT 18 1999

RECEIVED

TC 2800 MAIL ROOM

OCT 16 1999

RECEIVED

Dear Sir or Madam:

Enclosed please find the following:

- 1) Amendment (5 pages, in duplicate);
- 2) Transmittal Sheet (1 pg. in duplicate);
- 3) Return Receipt Postcard

We do not believe there to be any additional fees required for this filing. However, if any fees are required or if the amount submitted with this application exceeds the required amount, please charge such fees or credit such overpayment to our Deposit Account No. 03-0172. A duplicate of this letter is enclosed for accounting purposes.

Very truly yours,



James A. Rich

Enclosures

Certificate of Mailing

I hereby certify that this paper or fee is being deposited with the United States Postal Service, via First Class Mail to Addressee" under 37 CFR 1.10 on October 12, 1999 and is addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231

Signed: 

CERTIFICATE OF MAILING

I hereby certify that this document is being deposited with the U.S. Postal Service via First Class Mail under 37 CFR 1.10 on October 12, 1999 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

6B
RPh...
10/19/1999

JAMES A. RICH
Print Name

[Signature]
Signature

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Gedney et al.

Serial No: 09/004,524

Filed: January 8, 1998

For: **IC CHIP ATTACHMENT**

Reissue of U.S. Patent No. 5,483,421

Issued: January 9, 1996

Art Unit: 2835

Examiner: Donald A. Sparks

Attorney's Docket No:
EN9-91-022R
(21325/00276)



AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action of July 12, 1999, please amend this application as follows:

In the Specification

Please amend the paragraph at page 7, lines 7-18, which was amended in the Preliminary Amendment dated January 8, 1998, as follows:

In the present invention, the chip carrier 24 preferably is made of the same material as the circuit board, as will be described presently. If the chip carrier is not fashioned from the same material as the board, it must, in any event, have a similar coefficient of thermal expansion; i.e. the difference in the coefficient of thermal expansion between the carrier and the circuit board should not vary more than about 20%. The chip carrier and board are made from an organic dielectric material. In

RECEIVED
OCT 18 1999
TECHNOLOGY CENTER 2800
OCT 16 1999
TC 2800 MAIL ROOM
RECEIVED

b1